RELIABILITY REPORT
FOR
MAX9890BETA+
PLASTIC ENCAPSULATED DEVICES

November 18, 2008

MAXIM INTEGRATED PRODUCTS
120 SAN GABRIEL DR.
SUNNYVALE, CA 94086

Approved by
Ken Wendel
Quality Assurance
Director, Reliability Engineering
Conclusion

The MAX9890BETA+ successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim’s continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim’s quality and reliability standards.

Table of Contents

I. Device Description
   A. General
II. Manufacturing Information
III. Packaging Information
IV. Die Information
V. Quality Assurance Information
VI. Reliability Evaluation

I. Device Description

A. General

The MAX9890 provides click-and-pop suppression for devices such as CODECs with integrated headphone amplifiers that lack a clickless/popless startup/power-up or shutdown/power-down. The device controls the ramping of the DC bias voltage on the output-coupling capacitors and the application of the audio signal to ensure that no audible transients are present at the headphones. The MAX9890A features a 200ms startup time for use with up to 100µF coupling capacitors. The MAX9890B features a 330ms startup time for use with greater than 100µF coupling capacitors. The MAX9890 consumes 14µA of supply current and 0.001µA in shutdown, while contributing less than 0.003% THD+N into a 32 load. ESD (Human Body Model) protection circuitry on the outputs protect the MAX9890 and devices further up the signal chain from ESD strikes up to ±8kV. The MAX9890 is available in a miniature (1.5mm x 1.5mm x 0.6mm) 9-bump chip-scale package (UCSP(tm)), as well as an 8-pin TDFN package (3mm x 3mm x 0.8mm), and is specified for operation over the -40°C to +85°C extended temperature range.
II.  Manufacturing Information

A.  Description/Function: Audio Click-Pop Suppressor
B.  Process: B8
C.  Number of Device Transistors: 
D.  Fabrication Location: Texas
E.  Assembly Location: ISPL Philippines, UTL Thailand, Unisem Malaysia
F.  Date of Initial Production: July 25, 2003

III.  Packaging Information

A.  Package Type: 8-pin TDFN 3x3
B.  Lead Frame: Copper
C.  Lead Finish: 100% matte Tin
D.  Die Attach: Conductive Epoxy
E.  Bondwire: Gold (1 mil dia.)
F.  Mold Material: Epoxy with silica filler
G.  Assembly Diagram: #05-9000-0601
H.  Flammability Rating: Class UL94-V0
I.  Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C: Level 1
J.  Single Layer Theta Ja: 54°C/W
K.  Single Layer Theta Jc: 8.3°C/W
L.  Multi Layer Theta Ja: 41°C/W
M.  Multi Layer Theta Jc: 8.3°C/W

IV.  Die Information

A.  Dimensions: 61 X 61 mils
B.  Passivation: SiO2/ Si3N4 (Silicon nitride/Silicon dioxide)
C.  Interconnect: Aluminum/Si (Si = 1%) 
D.  Backside Metallization: None
E.  Minimum Metal Width: 0.8 microns (as drawn)
F.  Minimum Metal Spacing: 0.8 microns (as drawn)
G.  Bondpad Dimensions: 5 mil. Sq.
H.  Isolation Dielectric: SiO2
I.  Die Separation Method: Wafer Saw
V. Quality Assurance Information

A. Quality Assurance Contacts: Ken Wendel (Director, Reliability Engineering)
   Bryan Preeshl (Managing Director of QA)

B. Outgoing Inspection Level: 0.1% for all electrical parameters guaranteed by the Datasheet.
   0.1% For all Visual Defects.

C. Observed Outgoing Defect Rate: < 50 ppm

D. Sampling Plan: Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135°C biased (static) life test are pending. Using these results, the Failure Rate ($\lambda$) is calculated as follows:

$$\lambda = \frac{1}{MTTF} = \frac{1.83}{192 \times 4340 \times 96 \times 2}$$

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$$\lambda = 11.2 \times 10^{-9}$$

$$\lambda = 11.2 \text{ F.I.T.} (60\% \text{ confidence level @ 25°C})$$

The following failure rate represents data collected from Maxim’s reliability monitor program. Maxim performs quarterly 1000 hour life test monitors on its processes. This data is published in the Product Reliability Report found at http://www.maxim-ic.com/. Current monitor data for the B8 Process results in a FIT Rate of 2.71 @ 25C and 17.30 @ 55C (0.8 eV, 60% UCL)

B. Moisture Resistance Tests

The industry standard 85°C/85%RH or HAST testing is monitored per device process once a quarter.

C. E.S.D. and Latch-Up Testing

The AU16-2 die type has been found to have all pins able to withstand a HBM transient pulse of +/-2000V per Mil-Std 883 Method 3015.7. Latch-Up testing has shown that this device withstands a current of +/-250 mA.
<table>
<thead>
<tr>
<th>TEST ITEM</th>
<th>TEST CONDITION</th>
<th>FAILURE IDENTIFICATION</th>
<th>SAMPLE SIZE</th>
<th>NUMBER OF FAILURES</th>
</tr>
</thead>
<tbody>
<tr>
<td>Static Life Test (Note 1)</td>
<td>Ta = 135°C Biased   Time = 192 hrs.</td>
<td>DC Parameters &amp; functionality</td>
<td>96</td>
<td>0</td>
</tr>
<tr>
<td>Moisture Testing (Note 2)</td>
<td>Ta = 85°C RH = 85% Biased Time = 1000hrs.</td>
<td>DC Parameters &amp; functionality</td>
<td>77</td>
<td>0</td>
</tr>
<tr>
<td>Mechanical Stress (Note 2)</td>
<td>Temperature Cycle -65°C/150°C 1000 Cycles Method 1010</td>
<td>DC Parameters &amp; functionality</td>
<td>77</td>
<td>0</td>
</tr>
</tbody>
</table>

Note 1: Life Test Data may represent plastic DIP qualification lots.
Note 2: Generic Package/Process data